

## WHAT WE CLAIM IS:

1. A semiconductor device comprising:

a substrate;

5 a semiconductor chip having one surface bonded to a surface  
of the substrate; and

a warp preventing sheet bonded to the other surface of  
the semiconductor chip.

10 2. A semiconductor device according to Claim 1, wherein  
the warp preventing sheet has a coefficient of elasticity  
substantially equal to that of the substrate.

3. A semiconductor device according to Claim 1, wherein  
15 the warp preventing sheet has a coefficient of thermal expansion  
substantially equal to the of the substrate.

4. A semiconductor device according to Claim 1, wherein  
a base of the warp preventing sheet is made of material identical  
20 with that of a base of the substrate.

5. A semiconductor device according to Claim 1, wherein  
a base of each of the substrate and the warp preventing sheet  
is a polyimide resin.

6. A semiconductor device according to Claim 1, wherein the warp preventing sheet has a thickness substantially equal to that of the substrate.

5 7. A semiconductor device according to Claim 1, wherein the semiconductor device is a thin semiconductor device of a chip-size package type.

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